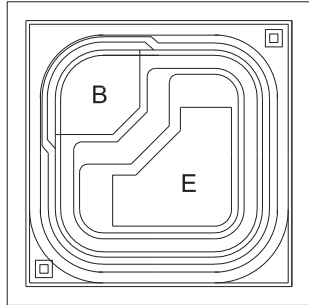


# CP788X-2N5087

## PNP - General Purpose Transistor Die

The CP788X-2N5087 is a silicon PNP transistor designed for general purpose applications.



BACKSIDE COLLECTOR R0

### MECHANICAL SPECIFICATIONS:

Die Size	13.7 x 13.7 MILS
Die Thickness	5.9 MILS
Base Bonding Pad Size	4.0 x 4.0 MILS
Emitter Bonding Pad Size	5.5 x 5.5 MILS
Top Side Metalization	Al-Si – 17,000Å
Back Side Metalization	Au – 9,000Å
Scribe Alley Width	1.8 MILS
Wafer Diameter	5 INCHES
Gross Die Per Wafer	91,469

### MAXIMUM RATINGS: ( $T_A=25^\circ\text{C}$ )

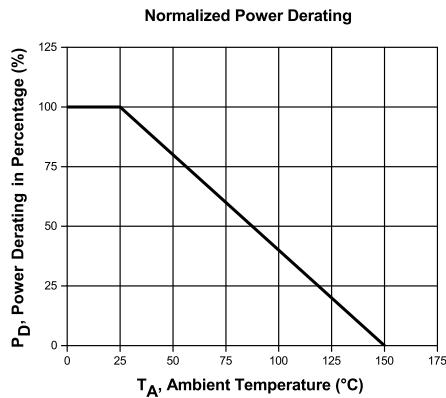
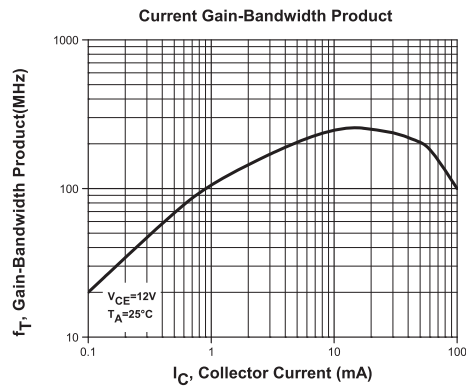
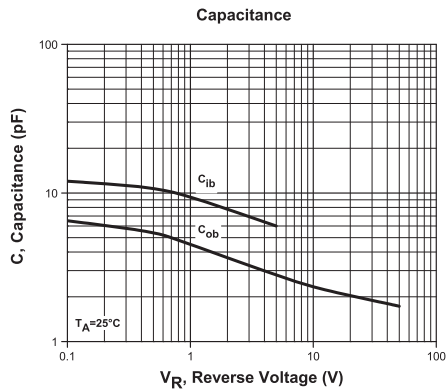
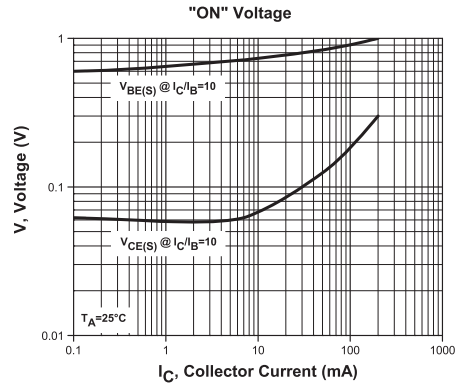
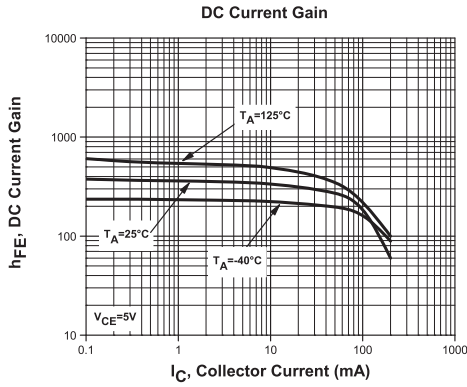
	SYMBOL		UNITS
Collector-Base Voltage	$V_{CBO}$	50	V
Collector-Emitter Voltage	$V_{CEO}$	50	V
Emitter-Base Voltage	$V_{EBO}$	3.0	V
Continuous Collector Current	$I_C$	50	mA
Operating and Storage Junction Temperature	$T_J, T_{stg}$	-65 to +150	$^\circ\text{C}$

### ELECTRICAL CHARACTERISTICS: ( $T_A=25^\circ\text{C}$ )

SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
$I_{CBO}$	$V_{CB}=35\text{V}$		50	nA
$I_{EBO}$	$V_{EB}=3.0\text{V}$		50	nA
$BV_{CBO}$	$I_C=100\mu\text{A}$	50		V
$BV_{CEO}$	$I_C=1.0\text{mA}$	50		V
$V_{CE(SAT)}$	$I_C=10\text{mA}, I_B=1.0\text{mA}$		0.30	V
$V_{BE(ON)}$	$V_{CE}=5.0\text{V}, I_C=1.0\text{mA}$		0.85	V
$h_{FE}$	$V_{CE}=5.0\text{V}, I_C=100\mu\text{A}$	250	800	
$h_{FE}$	$V_{CE}=5.0\text{V}, I_C=1.0\text{mA}$	250		
$h_{FE}$	$V_{CE}=5.0\text{V}, I_C=10\text{mA}$	250		
$f_T$	$V_{CE}=5.0\text{V}, I_C=500\mu\text{A}, f=20\text{MHz}$	40		MHz
$C_{ob}$	$V_{CB}=5.0\text{V}, I_E=0, f=100\text{kHz}$		4.0	pF

# CP788X-2N5087

## Typical Electrical Characteristics



## OUTSTANDING SUPPORT AND SUPERIOR SERVICES



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### PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

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### DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2<sup>nd</sup> day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

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### CONTACT US

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